

IN THE CLAIMS

- 1 (Currently Amended). At least one packaged integrated circuit comprising:
a semiconductor die;
a flexible substrate, said die attached to said substrate; ~~and~~
at least two buildup layers formed over said substrate, a cavity formed in said
buildup layers, and said die mounted in said cavity; and
a folded package.
- 2 (Original). The circuit of claim 1 including lands below said flexible substrate, said
lands coupled to solder balls.
- 3 (Original). The circuit of claim 1 wherein said flexible substrate is formed of
polyamide.
- 4 (Original). The circuit of claim 1 wherein said cavity is stepped.
- 5 (Original). The circuit of claim 4 including an interconnection layer between said
buildup layers.
- 6 (Original). The circuit of claim 5 including an interconnection layer between one of
said buildup layers and said flexible substrate.
- 7 (Original). The circuit of claim 6 including wire bonds from one of said
interconnection layers to said die.
- 8 (Original). The circuit of claim 7 including a die attach between said cavity and said
die.
- 9 (Original). The circuit of claim 1 wherein the upper surface of the upper buildup layer
is higher than the upper surface of said die.
- Claim 10 (Canceled).

11 (Currently Amended). A method comprising:
securing a semiconductor die within a cavity in a folded flexible package.

12 (Original). The method of claim 11 including securing said die in a stepped cavity.

13 (Original). The method of claim 11 including securing said die in a cavity formed by at least two buildup layers.

14 (Original). The method of claim 13 including providing interconnection layers between said buildup layers.

15 (Original). The method of claim 14 including providing an interconnection layer between a buildup layer and a flexible substrate.

16 (Original). The method of claim 11 including packaging said die at a level in said cavity below the upper surface of said cavity.

17 (Original). The method of claim 16 including wire bonding from said package to said die.

18 (Original). The method of claim 11 including forming a flexible substrate of polyamide in said package.

Claim 19 (Canceled).

20 (Currently Amended). A package comprising:
a flexible substrate; ~~and~~
a layer over said substrate, said layer having a cavity formed therein to receive a die; and
wherein said package is a folded package.

21 (Original). The package of claim 20 wherein said layer is formed of at least two buildup layers.

22 (Original). The package of claim 21 wherein said cavity is stepped.

23 (Original). The package of claim 20 including solder balls coupled thereto.

24 (Original). The package of claim 20 wherein said flexible substrate includes polyamide.

25 (Original). The package of claim 21 including an interconnection layer between said buildup layers.

26 (Original). The package of claim 25 including a pair of buildup layers over said flexible substrate.

27 (Original). The package of claim 25 including an interconnection layer between said substrate and one of said buildup layers.

28 (Original). The package of claim 20 including a die attach in said cavity.

Claim 29 (Canceled).